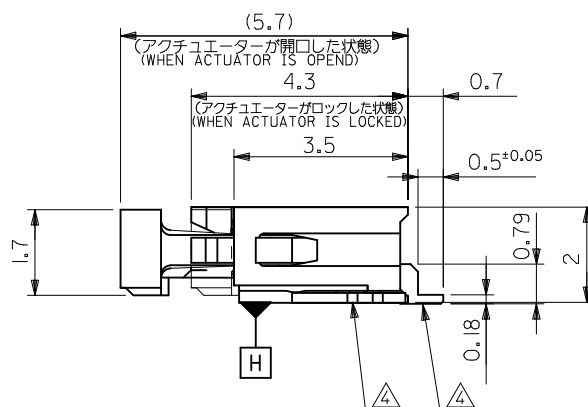
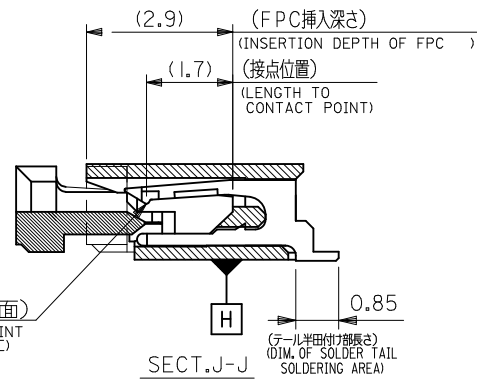




8.ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT

CONNECTOR SERIES NO. : 52745-**-17

EN-02JA(021)

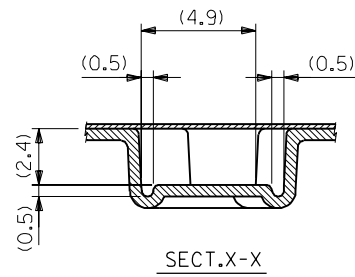
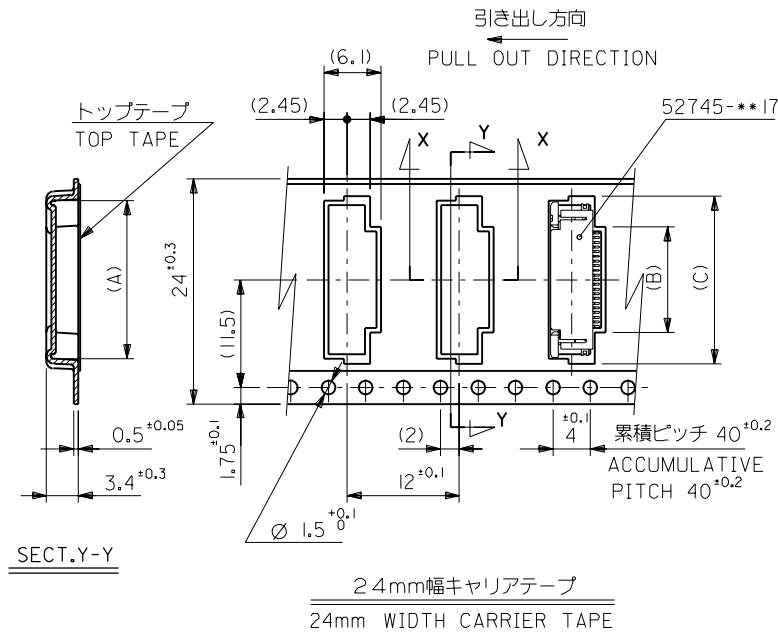
E

D

C
B
A
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

A

8 7 6 5 4 3 2 1



24	25.5	17.4	10.8	16.4	52745-2090	20
		16.9	10.3	15.9	-1990	19
		16.4	9.8	15.4	-1890	18
		15.9	9.3	14.9	-1790	17
		15.4	8.8	14.4	-1690	16
		14.9	8.3	13.9	-1590	15
		14.4	7.8	13.4	-1490	14
		13.9	7.3	12.9	-1390	13
		13.4	6.8	12.4	-1290	12
		12.9	6.3	11.9	-1190	11
		12.4	5.8	11.4	-1090	10
		11.9	5.3	10.9	-0990	9
		11.4	4.8	10.4	-0890	8
		10.9	4.3	9.9	-0790	7
		10.4	3.8	9.4	52745-0690	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CIRCUIT

角度 ANGLE	3°	変 更 REVIS	変 更 REVIS	変 更 REVIS	変 更 REVIS
30以上 OVER	+0.5	B	変 更 REVIS	(J40949)	00/12/20
10以上 30未満 OVER UNDER	+0.25	A	変 更 REVIS	(J40949)	94/11/17
10未満 UNDER	+0.2	O	新 規 作 成 RELEASE	(J40230)	94/3/24
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE

材料 MATERIAL	SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY 94/3/24 S.AIHARA	CHK'D BY 00/12/20 S.KUNISHI
APP'D BY 00/12/20 M.FUKUSHIMA	尺 度 SCALE

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstop Pkg	
DWG. NO. (SHEET 2 OF 3)	REV
SD-52745-***90	B

8 7 6 5 4 3 2 1

E

D

~MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

A

8

7

6

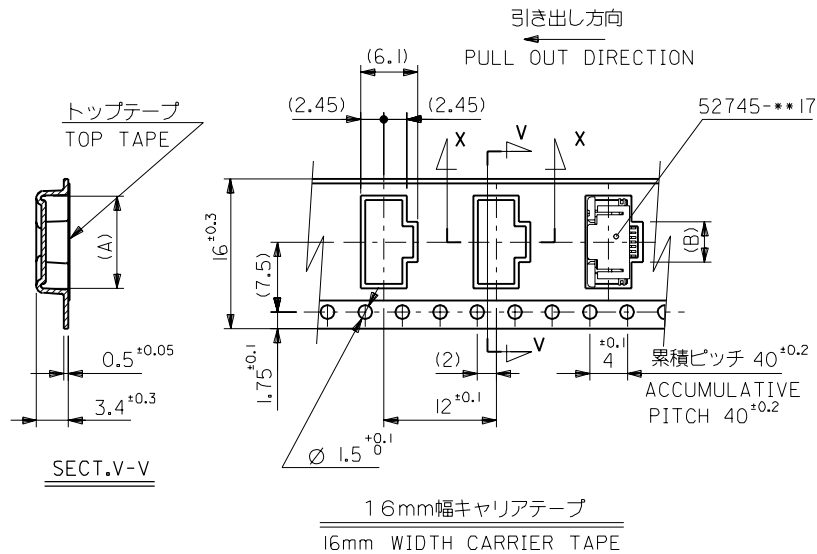
5

4

3

2

1



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

角度 ANGLE	3°				材料 MATERIAL	材料 MATERIAL
30°以上 OVER	+0.5	B	変更 REVISED	(JC2001-0425)	SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
10°以上 30°未満 OVER UNDER	+0.25	A	変更 REVISED	(J40949)	仕上げ FINISH	REVISE ONLY ON CAD SYSTEM
10°未満 UNDER	+0.2	O	新規作成 RELEASED	(J40230)	適用電線範囲 WIRE RANGE	TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstop Pkg
公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	DWG. NO. (SHEET 3 OF 3) REV SD-52745-***90 B

8

7

6

5

4

3

2

1

F

E

D

C

B

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F

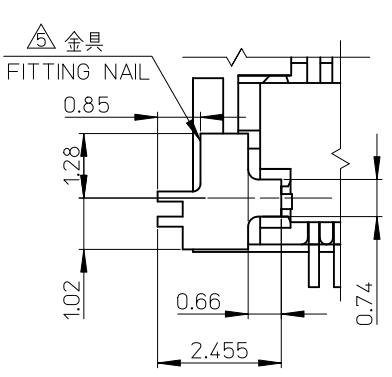
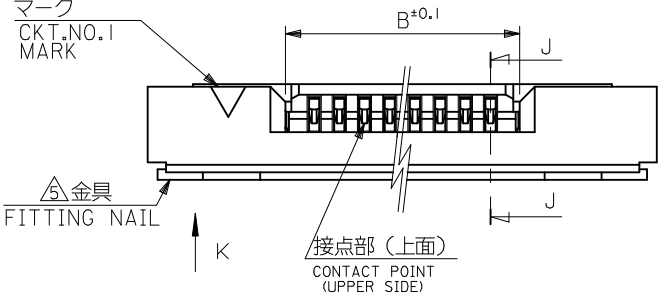
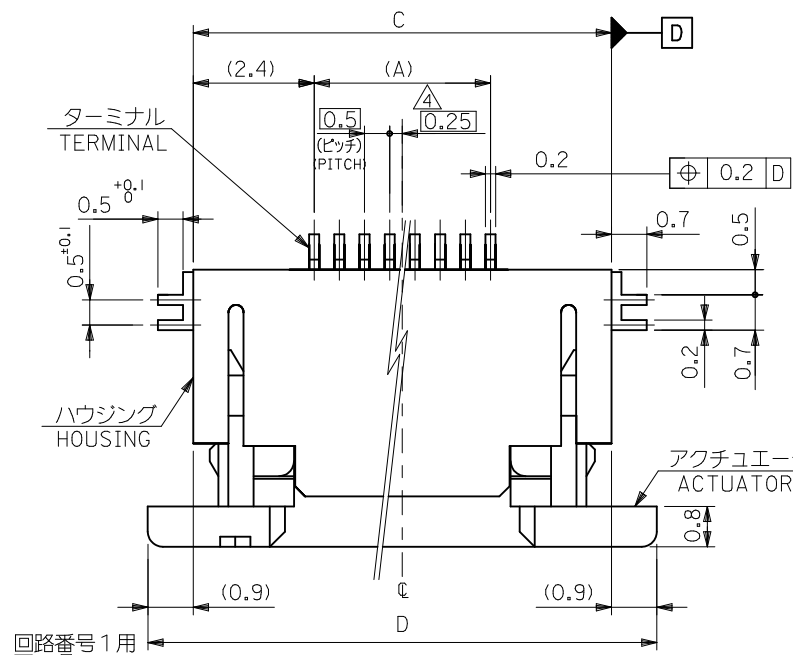
E

D

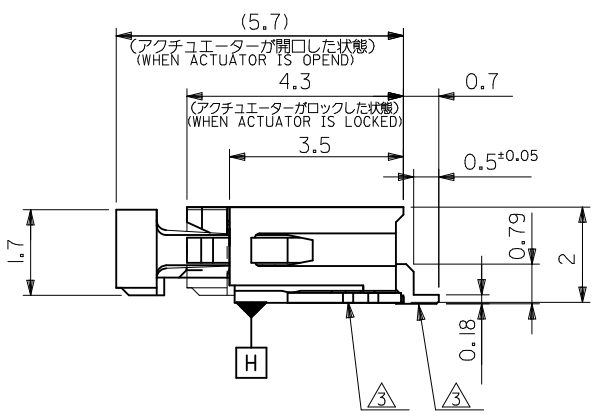
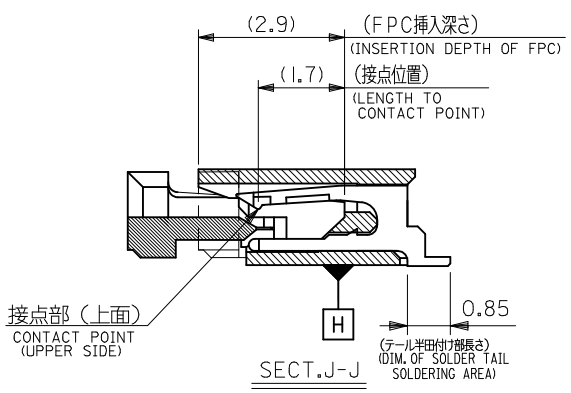
C

B

A



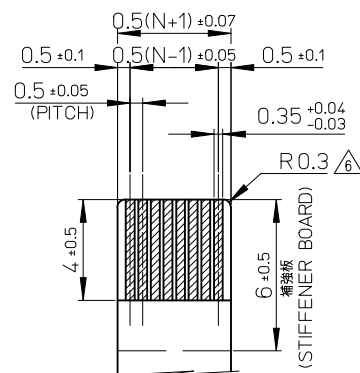
VIEW K
(金具部投影図)
(DETAIL OF FITTING NAIL)



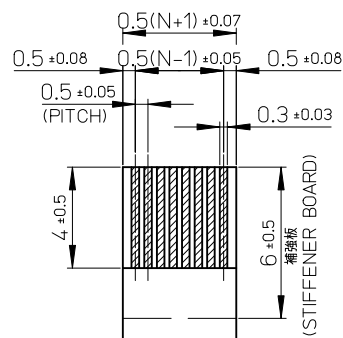
16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
15.1	13.3	9.65	8.5	52745-1890	18
14.6	12.8	9.15	8	52745-1790	17
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
13.1	11.3	7.65	6.5	52745-1490	14
12.6	10.8	7.15	6	52745-1390	13
12.1	10.3	6.65	5.5	52745-1290	12
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**17

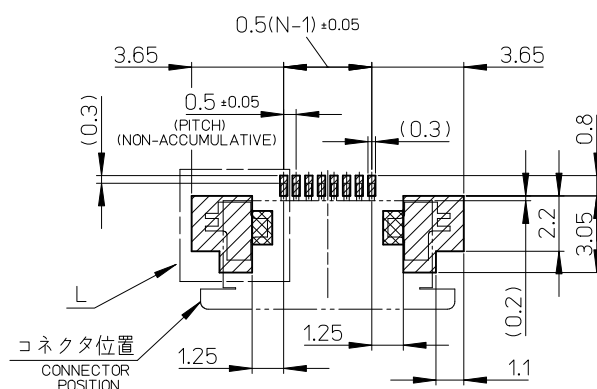
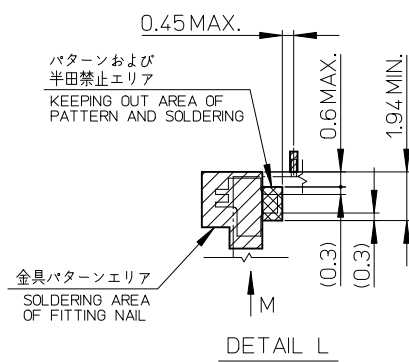
REVISED EC NO: J2011-0041 DRAWN:HYOSHINO CHKD:HIJIMA APPR:KMORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	± 0.2	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING					
		10 OVER 30 UNDER	± 0.25	CHECKED BY SKUNISHI	DATE 2000/06/30						
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/07/16						
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52745-054		1 OF 2			
REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3+0.03/-0.03

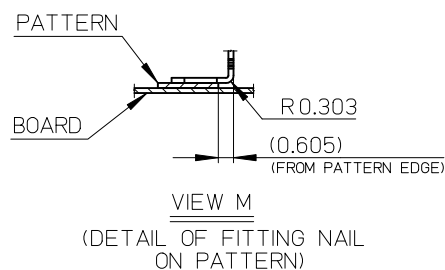


適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3+0.03/-0.03



参考基板レイアウト
(マウント面)

RECOMMENDED P.C.BOARD
PATTERN DIMENSION(REF.)
(MOUNTING SIDE)



注記NOTES

1. 使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル: リン青銅、銅下地半田めっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
金具: リン青銅、銅下地半田めっき (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE,ACTUATOR OF PART
NO.52745-**17 SHOULD BE LOCKED.

3. NO.32745-***17 SHOELED-BE LOCKER.
ソルダーテール半付け面のズレ量、及び金具半付け面のズレ量は、
基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM
DATUM-H

UPPER_DIRECTION:0 1MAXIMUM

LOWER DIRECTION:0.15 MAXIMUM

△₄ 偶数極に適用

APPLY FOR EVEN CIRCUIT.

△5 ハ・ターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

△6 R0.3は、FPCの胴体部にかからないこと
R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて：

打抜き方向は導体側から補強板を推奨致します。

補強フィルム材質はポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL :

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED	EC NO: J2011-0041	DRAWN:HYOSHINO CHKD:H.IJIMA APPR:KMORI KAWA	2010/07/08 2010/07/08 2010/07/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
					10 UNDER	± ---	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING			
					10 OVER 30 UNDER	± ---	CHECKED BY SKUNISHI	DATE 2000/06/30				
					30 OVER	± ---	APPROVED BY KMORI KAWA	DATE 2010/07/16				
					ANGULAR ±3 °		MATERIAL NO.					DOCUMENT NO.
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52745-054			2 OF 2
REV						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				